



AMD Server Solution 2023

Jun.2023

Product Portfolio



R-Series Affordable and expandable rackmount servers, offering easeof-use, low power consumption and quiet operation



E-Series

Edge computing is a distributed computing paradigm which brings computation and data storage closer to the location where it is needed, to improve response times and save bandwidth



H-Series

Compact and scalable systems providing higher density computing power in a smaller footprint for cloud and other scale-out computing applications



OCP-Series

A datacenter solution simple in design, but also highly efficient in power consumption, computing power and configuration



G-Series

Versatile and scalable high performance computing with leading efficiency and performance. Ideal for datacenters



Following high core count CPU & high TDP developed, traditional air cooling can not afford anymore. L-series provide more efficient cooling to the system and keep the high computing performance at all times.



S-Series

Storage optimized servers that offer a high data density design, configuration flexibility, and HA and reliability features for data integrity

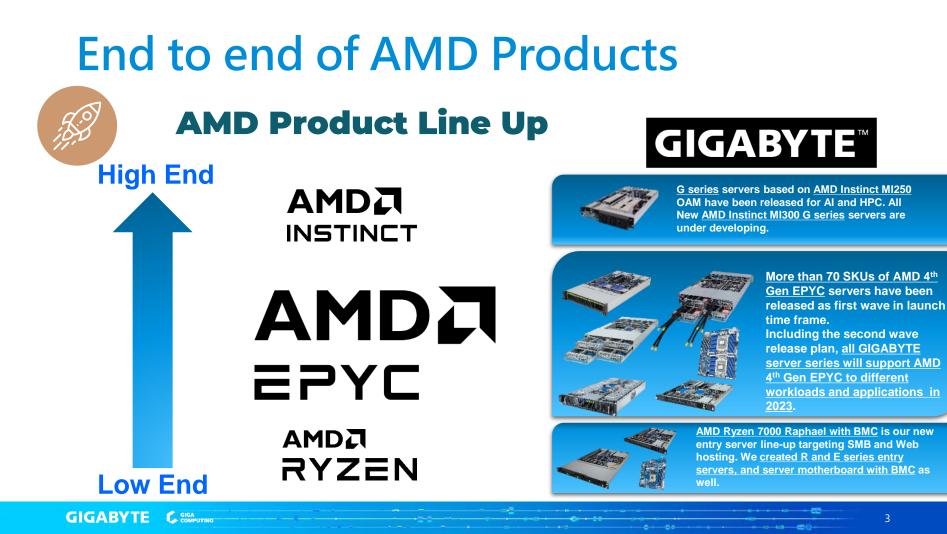


More than L-series, Immersion cooling uses different ways to cool down. Not just CPU, but also the whole system's component. Special enclosure and tray design make all systems stay at the lowest temperature to compute.



W-Series

A range of tower servers suitable for an office environment, from entry level to high end computing and HPC



GIGABYTE^{**}

GPU Solution

Gigabyte GPU Server Architecture (G)

2 x Low-profile Slot (@Gen4)





New: OAM GPU in 2U & Thermal Optimized SKU



Flexible Redundant PSU

4 x AMD Instinct MI250 OAM GPU modules in 2U



G262 Series

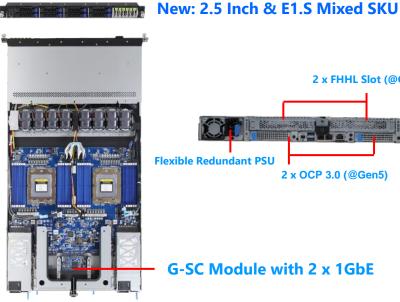


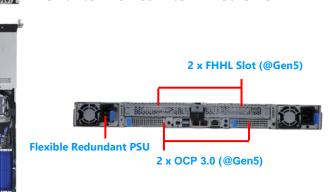




EPYC Solution

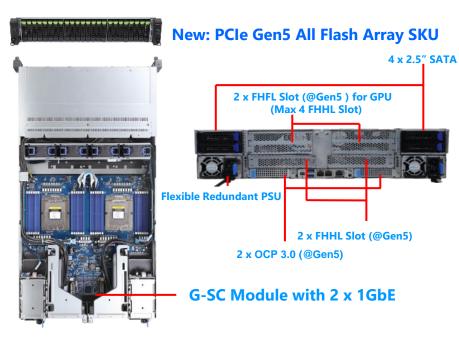
Gigabyte 3rd Gen Server Architecture (R)





G-SC Module with 2 x 1GbE

R183 Series



R283 Series



Gigabyte 3rd Gen Server Architecture (R)



R163 Series



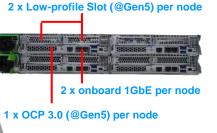
Gigabyte 3rd Gen Server Architecture(H)





GIGABYTE

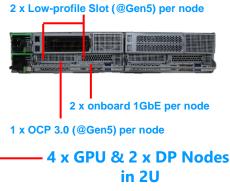




4 x DP Nodes in 2U



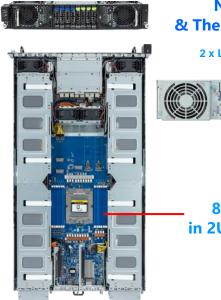
New: Thermal Optimized SKU



H273 Series



Gigabyte 3rd Gen Server Architecture(G)



New: PCIe Gen5 & Thermal Optimized SKU

2 x Low-profile Slot (@Gen5)

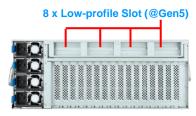


2 x onboard 10GbE

8 x Double-slot GPU in 2U (Both UP & DP SKUs)



New: PCle Gen5 & Thermal Optimized SKU

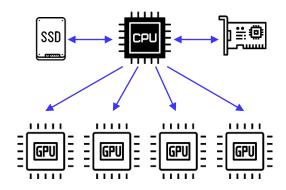


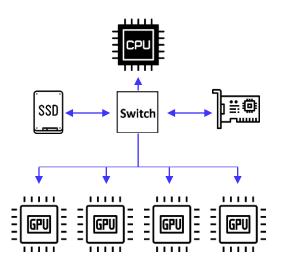
8-10 x Double-slot GPU in 4U (DP 24 & 48 DIMMs SKUs)

G493 Series

G293 Series

One to One Communication

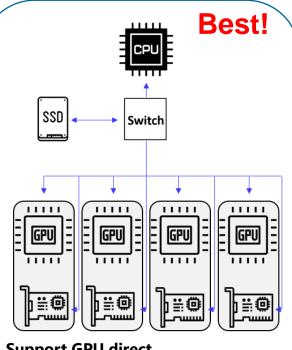




IO devices and GPUs communication on <u>CPU</u>

GIGABYTE

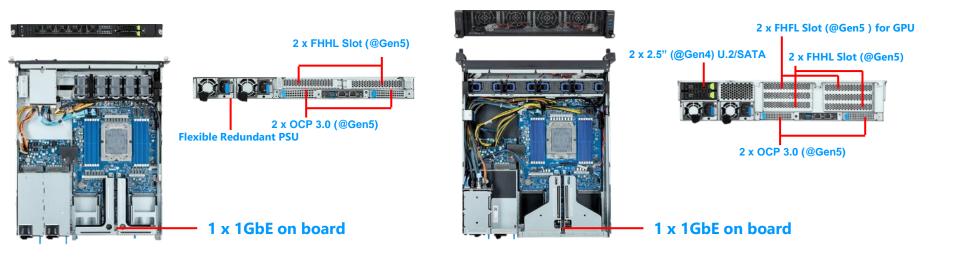
Support GPU direct IO devices and GPUs communication via <u>PCIe Switch</u>



Support GPU direct GPU to IO device ratio is one to one



Gigabyte 3rd Gen Server Architecture(E)

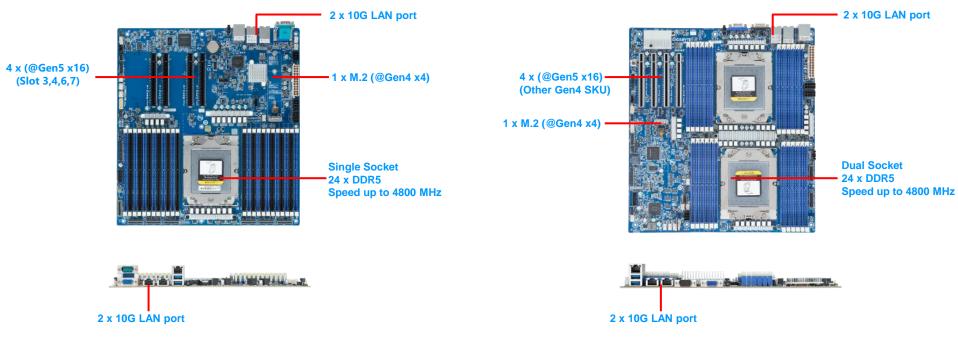


E163 Series





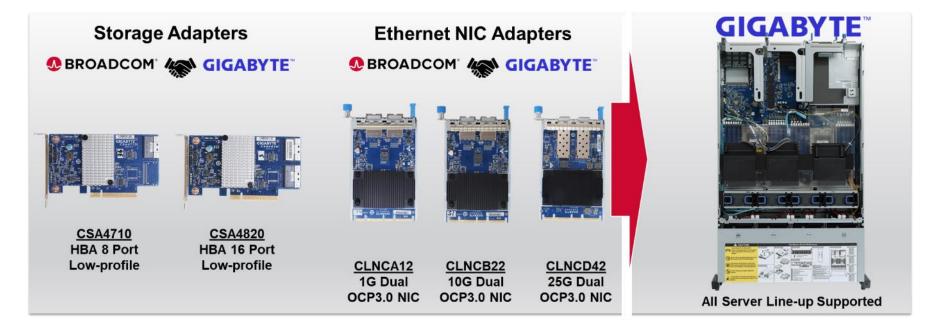
Gigabyte 3rd Gen Server Board (M)



MZ33 Series (EATX)



Total Hardware Solution – Accessories



Fit Broadcom's Storage and Ethernet NIC Solutions into GIGABYTE's Servers GIGABYTE created own OCP3.0 & LP cards with Broadcom's chips





Ryzen Solution

Gigabyte Entry Server Architecture (R)



New: PCIe Gen5 Entry Solution SKU

1 x FHHL Slot (@Gen5) 1 x FHFL Slot (@Gen5)



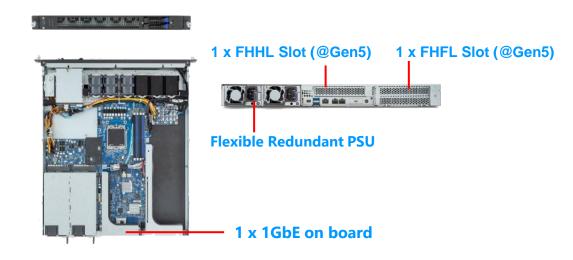
Flexible Redundant PSU

- 2 x 10GbE on board 2 x 1GbE on board

R133 Series



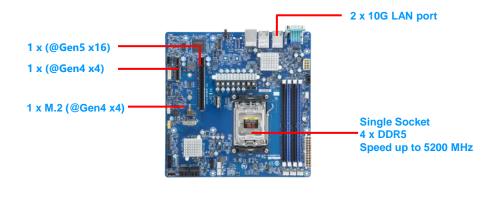
Gigabyte Edge Server Architecture(E)



E133 Series



Gigabyte Entry Server Board (M)





MC13 Series (mATX)



a man la mat



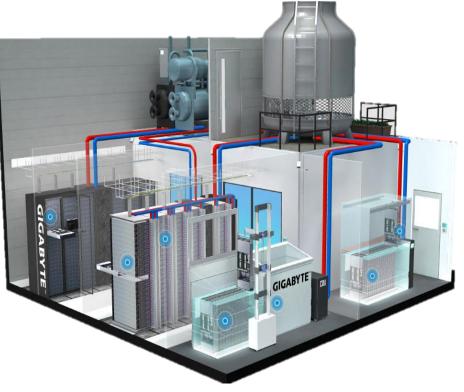


Advanced Cooling Solution

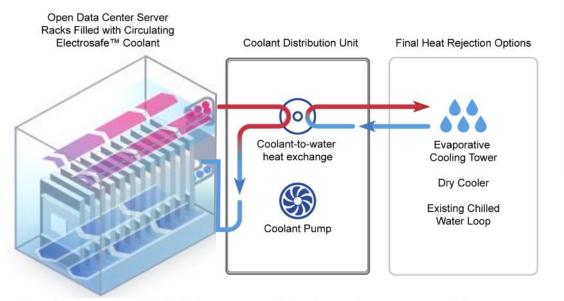
Advanced Cooling Solution







1 Phase Immersion Cooling Architecture



· Heated coolant exits top of rack. Coolant returns to rack from heat exchanger at user-specified temperature.



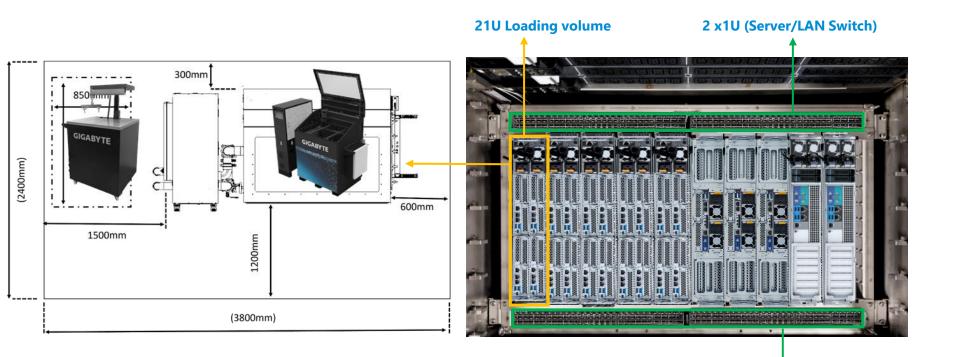


1-Phase Immersion Cooling Solution – 25U Tank



ltem	SPEC
Server Support (U)	21U (Inner) + 4U (1U)
Cooling Power (kW)	80 kW
Unit Size (m)	Tank = 0.91(L) x 1.28(W) x 1.49(H) CDU = 0.90(L) x 0.55(W) x 1.62(H)
Unit Weight (kg)	Tank = 1100 kg (w/o Coolant) CDU = 300 kg
Coolant Tank Volume (L)	800 Litter
Power Plug	CE Type x 3 Plug 3P+N+E 63A IEC 60309
Power	AC 380-400V 63A 50/60Hz
Depth Supported	900 mm
Cooling Pipe Size	BSP 2"
Cooling Water Temp(°C) - Inlet	35°C
Cooling Water Flow (LPM)	240 LPM

1-Phase Immersion cooling Solution – Situation

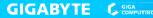


2 x1U (Server/LAN Switch)

1-Phase Immersion Cooling Solution – 4U7KW tank

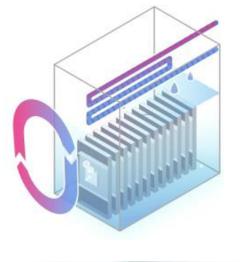


Item	SPEC
Server support (U)	4U
Cooling Power (kW)	7kW
Tank Size (m)	1.0(W) x 1.2(D) x 1.42(H)
Tank Weight (kg)	400 kg (w/o coolant)
Coolant Volume (L)	171 Litter (151kg)
Power Plug	CE Type x 1 Plug, 2P + N +E 16A IEC 60309
Power	CE Type x 1 Plug, AC 380-400V 50Hz
Power Usage	1.5 kW
Ambient Temp (°C)	5°C ~ 30°
Max Flow Rate	35 LPM
Oil Inlet Temp	30°C



2-Phase Immersion Cooling Architecture

Two-Phase Immersion Cooling - Up to 250 kW/Rack



The Passive 2-Phase Immersion Cooling Cycle

Vapor condenses on coil or lid condenser

Fluid recirculates passively to bath

Vapor rises to top



Heat generated on chip and fluid turns into vapor

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Flexible Business



Server Board Only



Barebone (L6)







Accelerator

Server System (L10)



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